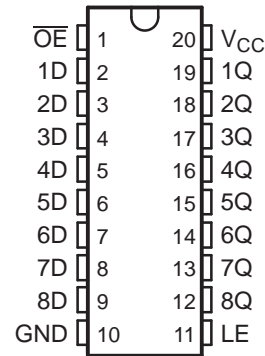


## OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

### FEATURES

- Qualified for Automotive Applications
- Operating Range 2-V to 5.5-V  $V_{CC}$
- 3-State Outputs Directly Drive Bus Lines

PW PACKAGE  
(TOP VIEW)



### DESCRIPTION

The SN74AHC573 is an octal transparent D-type latch designed for 2-V to 5.5-V  $V_{CC}$  operation.

When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is low, the Q outputs are latched at the logic levels of the D inputs.

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

$\overline{OE}$  does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

### ORDERING INFORMATION<sup>(1)</sup>

$T_A$	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	TSSOP – PW	Reel of 2000	SN74AHC573QPWRQ1	HA573Q

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).

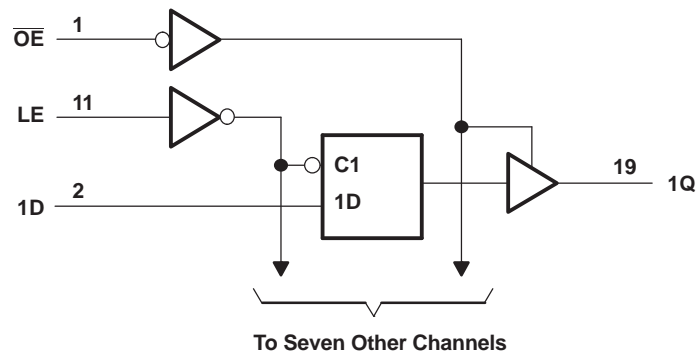
(2) Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

### FUNCTION TABLE (EACH LATCH)

INPUTS			OUTPUT Q
$\overline{OE}$	LE	D	
L	H	H	H
L	H	L	L
L	L	X	$Q_0$
H	X	X	Z



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**LOGIC DIAGRAM (POSITIVE LOGIC)****Absolute Maximum Ratings<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	-0.5	7	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	7	V
$V_O$	Output voltage range <sup>(2)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$	-20	mA
$I_{OK}$	Output clamp current	$V_O < 0$ or $V_O > V_{CC}$	$\pm 20$	mA
$I_O$	Continuous output current	$V_O = 0$ to $V_{CC}$	$\pm 25$	mA
Continuous current through $V_{CC}$ or GND			$\pm 75$	mA
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>	PW package	83	$^{\circ}\text{C}/\text{W}$
ESD rating <sup>(4)</sup>		Human-Body Model	1 (H1C)	kV
		Charged-Device Model	1 (C5)	
		Machine Model	200 (M3)	V
$T_{stg}$	Storage temperature range	-65	150	$^{\circ}\text{C}$

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.
- (4) ESD protection level per AEC Q100 classification

**Recommended Operating Conditions<sup>(1)</sup>**

		–40°C to 125°C		–40°C to 85°C		UNIT
		MIN	MAX	MIN	MAX	
V <sub>CC</sub>	Supply voltage	2	5.5	2	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5	1.5		V
		V <sub>CC</sub> = 3 V	2.1	2.1		
		V <sub>CC</sub> = 5.5 V	3.85	3.85		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V		0.5	0.5	V
		V <sub>CC</sub> = 3 V		0.9	0.9	
		V <sub>CC</sub> = 5.5 V		1.65	1.65	
V <sub>I</sub>	Input voltage	0	5.5	0	5.5	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2 V		–50	–50	μA
		V <sub>CC</sub> = 3.3 V ± 0.3 V		–4	–4	mA
		V <sub>CC</sub> = 5 V ± 0.5 V		–8	–8	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2 V		50	50	μA
		V <sub>CC</sub> = 3.3 V ± 0.3 V		4	4	mA
		V <sub>CC</sub> = 5 V ± 0.5 V		8	8	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 3.3 V ± 0.3 V		100	100	ns/V
		V <sub>CC</sub> = 5 V ± 0.5 V		20	20	
T <sub>A</sub>	Operating free-air temperature	–40	125	–40	85	°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			–40°C to 125°C		–40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = –50 μA	2 V	1.9	2		1.9		1.9	V	
		3 V	2.9	3		2.9		2.9		
		4.5 V	4.4	4.5		4.4		4.4		
	I <sub>OH</sub> = –4 mA	3 V		2.58		2.48		2.48		
		4.5 V		3.94		3.8		3.8		
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	2 V			0.1		0.1	0.1	V	
		3 V			0.1		0.1	0.1		
		4.5 V			0.1		0.1	0.1		
	I <sub>OL</sub> = 4 mA	3 V			0.36		0.5	0.44		
		4.5 V			0.36		0.5	0.44		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	±1	μA	
I <sub>OZ</sub>	V <sub>I</sub> = V <sub>IL</sub> or V <sub>IH</sub> , V <sub>O</sub> = V <sub>CC</sub> or GND	5.5 V			±0.25		±2.5	±2.5	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			4		40	40	μA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		2.5	10			10	pF	
C <sub>o</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	5 V		3.5					pF	

## Timing Requirements

over recommended operating free-air temperature range,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see [Figure 1](#))

		$T_A = 25^\circ\text{C}$		$-40^\circ\text{C to } 125^\circ\text{C}$		$-40^\circ\text{C to } 85^\circ\text{C}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
$t_w$	Pulse duration, LE high	5		5		5		ns
$t_{su}$	Setup time, data before LE↓	3.5		3.5		3.5		ns
$t_h$	Hold time, data after LE↓	1.5		1.5		1.5		ns

## Timing Requirements

over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see [Figure 1](#))

		$T_A = 25^\circ\text{C}$		$-40^\circ\text{C to } 125^\circ\text{C}$		$-40^\circ\text{C to } 85^\circ\text{C}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
$t_w$	Pulse duration, LE high	5		5		5		ns
$t_{su}$	Setup time, data before LE↓	3.5		3.5		3.5		ns
$t_h$	Hold time, data after LE↓	1.5		1.5		1.5		ns

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C to } 125^\circ\text{C}$		$-40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	D	Q	$C_L = 50\text{ pF}$	9.5	14.5		1	16.5	1	16.5	ns
$t_{PHL}$				9.5	14.5		1	16.5	1	16.5	
$t_{PLH}$	LE	Q	$C_L = 50\text{ pF}$	10.1	15.4		1	17.5	1	17.5	ns
$t_{PHL}$				10.1	15.4		1	17.5	1	17.5	
$t_{PZH}$	$\overline{OE}$	Q	$C_L = 50\text{ pF}$	9.8	15		1	17	1	17	ns
$t_{PZL}$				9.8	15		1	17	1	17	
$t_{PHZ}$	$\overline{OE}$	Q	$C_L = 50\text{ pF}$	10.7	14.5		1	16.5	1	16.5	ns
$t_{PLZ}$				10.7	14.5		1	16.5	1	16.5	

## Switching Characteristics

over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see [Figure 1](#))

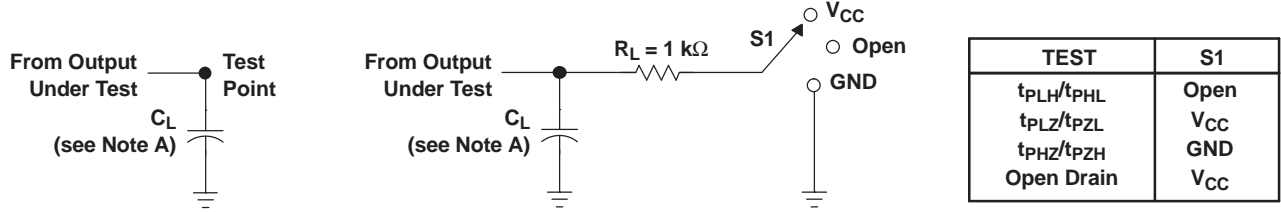
PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C to } 125^\circ\text{C}$		$-40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	D	Q	$C_L = 50\text{ pF}$	6	8.8		1	10	1	10	ns
$t_{PHL}$				6	8.8		1	10	1	10	
$t_{PLH}$	LE	Q	$C_L = 50\text{ pF}$	6.5	9.7		1	11	1	11	ns
$t_{PHL}$				6.5	9.7		1	11	1	11	
$t_{PZH}$	$\overline{OE}$	Q	$C_L = 50\text{ pF}$	6.7	9.7		1	11	1	11	ns
$t_{PZL}$				6.7	9.7		1	11	1	11	
$t_{PHZ}$	$\overline{OE}$	Q	$C_L = 50\text{ pF}$	6.7	9.7		1	11	1	11	ns
$t_{PLZ}$				6.7	9.7		1	11	1	11	

## Operating Characteristics

$V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

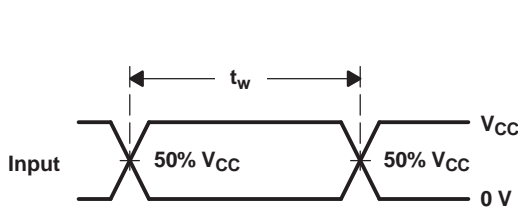
PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	No load, $f = 1\text{ MHz}$	16	pF

PARAMETER MEASUREMENT INFORMATION

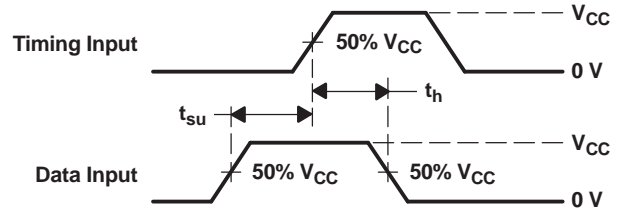


LOAD CIRCUIT FOR  
TOTEM-POLE OUTPUTS

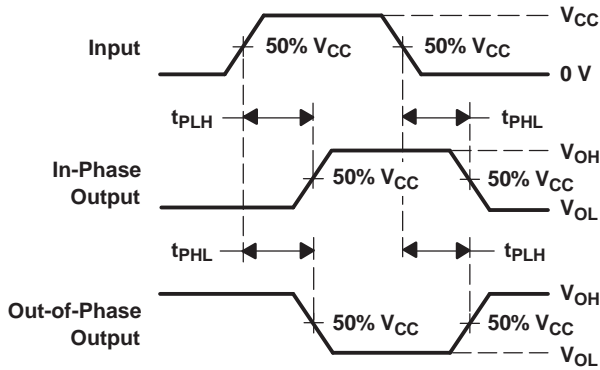
LOAD CIRCUIT FOR  
3-STATE AND OPEN-DRAIN OUTPUTS



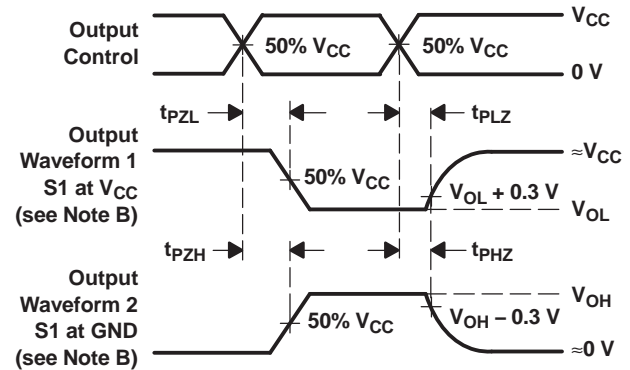
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 3$  ns,  $t_f \leq 3$  ns.  
 D. The outputs are measured one at a time, with one input transition per measurement.  
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuits and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
SN74AHC573QPWRG4Q1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74AHC573QPWRQ1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**OTHER QUALIFIED VERSIONS OF SN74AHC573-Q1 :**

● Catalog: [SN74AHC573](#)

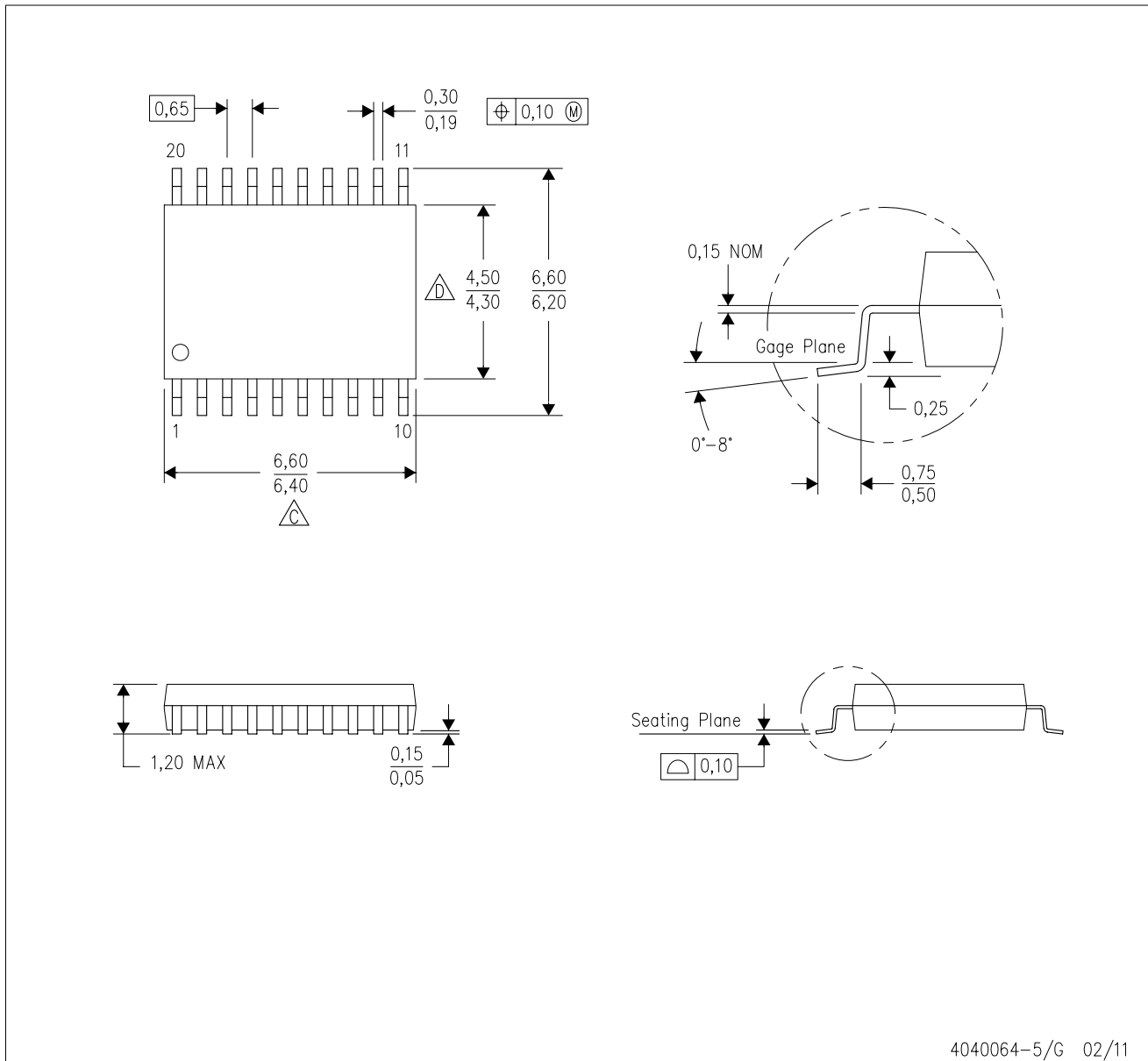
● Military: [SN54AHC573](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4040064-5/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153



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